

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Huay Huay Sim</td> <td>01/09/2009</td> </tr> <tr> <td>Chong Kooi Chee</td> <td>01/09/2009</td> </tr> <tr> <td>Kein Fee Liew</td> <td>01/09/2009</td> </tr> </tbody> </table>		Name	Execution Date	Huay Huay Sim	01/09/2009	Chong Kooi Chee	01/09/2009	Kein Fee Liew	01/09/2009				
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Intel Corporation</td> </tr> <tr> <td>Street Address:</td> <td>2200 Mission College Boulevard</td> </tr> <tr> <td>Internal Address:</td> <td>M/S SC4-202</td> </tr> <tr> <td>City:</td> <td>Santa Clara</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95052-5326</td> </tr> </table>		Name:	Intel Corporation	Street Address:	2200 Mission College Boulevard	Internal Address:	M/S SC4-202	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95052-5326
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CORRESPONDENCE DATA													
Fax Number: (503)591-7892 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 503-264-8286 Email: derek.s.watson@intel.com Correspondent Name: Intel Corporation c/o Intellevate LLC Address Line 1: P.O. Box 52050 Address Line 4: Minneapolis, MINNESOTA 55402													
ATTORNEY DOCKET NUMBER:	P27081												
NAME OF SUBMITTER:	David L. Guglielmi												
Total Attachments: 2 source=P27081_Assignment#page1.tif													

CH \$40.00 12164390

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PATENT
REEL: 022097 FRAME: 0590

Attorney Docket No.: P27081

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Huay Huay Sim; Chong Kooi Chee; Kein Fec Liew

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

**BACKSIDE MOLD PROCESS FOR ULTRA THIN SUBSTRATE AND PACKAGE ON
PACKAGE ASSEMBLY**

(I hereby authorize and request my attorney, associated with Customer Number 59796, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on June 30, 2008 as

United States Application Number 12/164,390 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and

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improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

May
Huey Huey Sim

01/09/2009
(Today's Date)

[Signature]
Chong Kool Chee

01/09/2009
(Today's Date)

[Signature]
Kien Fee Liew

01/09/2009
(Today's Date)